



## PRESS RELEASE

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### **Ellipsiz To Return To Growth With Completed Restructuring**

*New business divisions and integration of engineering solutions form launch pad for serving China and Asian semiconductor industries*

**Singapore, August 19, 2003** After a year of intensive restructuring, semiconductor engineering solutions provider, Ellipsiz Ltd, is poised to return to the black, and to a new phase of accelerated growth. In its financial year which ended in June 2003, a double-dip in the weak industry recovery, coupled with provisions for potential asset impairment and retrenchment costs associated with restructuring its loss-generating advanced packaging division, resulted in a full-year loss of \$18.18m on revenues of \$51.19m.

“We are in a much stronger position compared to a year ago,” said Chairman and CEO, Xavier Chong. “We were like a leaking boat with two malfunctioning engines and weights onboard before the restructuring. In the past year, we have re-tuned our business model for our Advanced Packaging arm, cut unnecessary overheads and expenses, and started defining and developing scalable integrated engineering solutions from our current products.

“These steps to clean house and to rebuild new engines will stand us in good stead to ride on the recovery which is underway, and even more importantly, for the future. The goal is to grow strong business units that can scale and compete in the regional markets, especially China. China’s semiconductor industry is continuing to grow by leaps and bounds, with government, foreign investors and local companies working closely together. There is a window of opportunity for an engineering solutions provider like Ellipsiz to offer our knowhow and networks in the regional semiconductor supply chain, and we are starting to gain traction in key semiconductor cities such as Shanghai and Shenzhen.”

He added, "While our business in Southeast Asia will rebound with the strengthening industry recovery, we see China as a key growth market for us in the foreseeable future."

Besides exporting its more established solutions for wafer manufacturing, such as its failure analysis lab, and total chemicals and abatement management solutions for wafer fabrication plants, Ellipsiz has hatched a new Design-To-Silicon Division, which is in its early formative stages, and combined its remodelled advanced packaging business with its test solutions business under a new grouping, the Test and Assembly Division.

"Our advanced packaging business is now rebuilt around a licensing model that we term IOT (Integrate-Operate-Transfer). We offer our proprietary wafer bumping technology to partners, who may be wafer fabs or test and assembly houses, through a process whereby we integrate the equipment sets into a bump line, provide training, get the line operational, and then transfer it to the licensee," explained Chong. "We are now seeing clear signs of demand for this solution, with flip-chip packaging becoming mainstream among integrated device manufacturers and fabless companies, for new communications, consumer and computer products."

With the restructuring completed, and the foundation for new divisions laid, Chong is confident that the worst is over. "The skies are turning blue again for the industry, especially over China, and we are now like a speedboat, rebuilt and streamlined, with old engines retuned and new engines added. We are now back in the race again."

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#### **About Ellipsiz Ltd.**

*The Ellipsiz Group is a leading engineering and advanced packaging solutions provider to the semiconductor industry in Asia. The holding company, Ellipsiz Ltd., was listed on SGX in*

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*July 2000. Among its engineering solutions are the sale and support of semiconductor equipment and chemicals, turnkey failure analysis laboratories, and total chemicals management (TCM). It also offers advanced packaging services such as wafer bumping and System-in-Package manufacturing.*

*The Group has operations in Singapore, Malaysia, Taiwan and China. More information on the Group is posted on its website at [www.ellipsiz.com](http://www.ellipsiz.com)*

### **About Shenzhen IC Design Industrial Base**

*SZICB, an affiliate of Shenzhen Sciences and Technology Bureau, was established by Shenzhen Municipal Government. It specializes in serving all IC design houses located in Shenzhen, supporting research and development of IC chips, cooperating with universities to build key laboratories, building IC verification and test environment and administering the government's capital. For more information, please visit [www.southic.com](http://www.southic.com)*